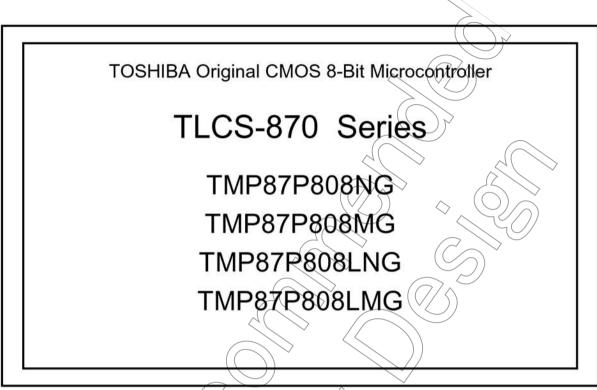
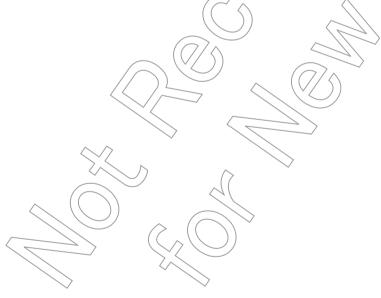
TOSHIBA





TOSHIBA CORPORATION

Semiconductor Company

Document Change Notification

The purpose of this notification is to inform customers about the launch of the Pb-free version of the device. The introduction of a Pb-free replacement affects the datasheet. Please understand that this notification is intended as a temporary substitute for a revision of the datasheet.

Changes to the datasheet may include the following, though not all of them may apply to this particular device.

1. Part number

Example: TMPxxxxxxFG

All references to the previous part number were left unchanged in body text. The new part number is indicated on the prelims pages (cover page and this notification).

2. Package code and package dimensions

Example: LQFP100-P-1414-0.50C (LQFP100-P-1414-0.50F)

All references to the previous package code and package dimensions were left unchanged in body text. The new ones are indicated on the prelims pages.

3. Addition of notes on lead solderability

Now that the device is Pb-free, notes on lead solderability have been added.

4. RESTRICTIONS ON PRODUCT USE

The previous (obsolete) provision might be left unchanged on page 1 of body text. A new replacement is included on the next page.

5. Publication date of the datasheet

The publication date at the lower right corner of the prelims pages applies to the new device.

I 2008-03-06

1. Part number

2. Package code and dimensions

Previous Part Number (in Body Text)	Previous Package Code (in Body Text)	New Part Number	New Package Code	ОТР
TMP87P808N	P-SDIP28-400-1.78	TMP87P808NG	SDIP28-P-400-1.78	_
TMP87P808M	P-SOP28-450-1.27	TMP87P808MG	SOP28-P-450-1.27B	_
TMP87P808LN	P-SDIP28-400-1.78	TMP87P808LNG	SDIP28-P-400-1.78	_
TMP87P808LM	P-SOP28-450-1.27	TMP87P808LMG	SOP28-P-450-1.27B	_

^{*:} For the dimensions of the new package, see the attached Package Dimensions diagram.

3. Addition of notes on lead solderability

The following solderability test is conducted on the new device.

Lead solderability of Pb-free devices (with the G suffix)

Test	Test Conditions	Remark
Solderability	(1) Use of Lead (Pb) -solder bath temperature = 230°C -dipping time = 5 seconds -the number of times = once -use of R-type flux (2) Use of Lead (Pb)-Free -solder bath temperature = 245°C -dipping time = 5 seconds -the number of times = once -use of R-type flux	Leads with over 95% solder coverage till lead forming are acceptable.

4. RESTRICTIONS ON PRODUCT USE

The following replaces the "RESTRICTIONS ON PRODUCT/USE" on page 1 of body text.

RESTRICTIONS ON PRODUCT USE

20070701-EN

- The information contained herein is subject to change without notice.
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 devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical
 stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety
 in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such
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- Please contact your sales representative for product-by-product details in this document regarding RoHS
 compatibility. Please use these products in this document in compliance with all applicable laws and regulations that
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 as a result of noncompliance with applicable laws and regulations.
- For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance/Handling Precautions.

5. Publication date of the datasheet

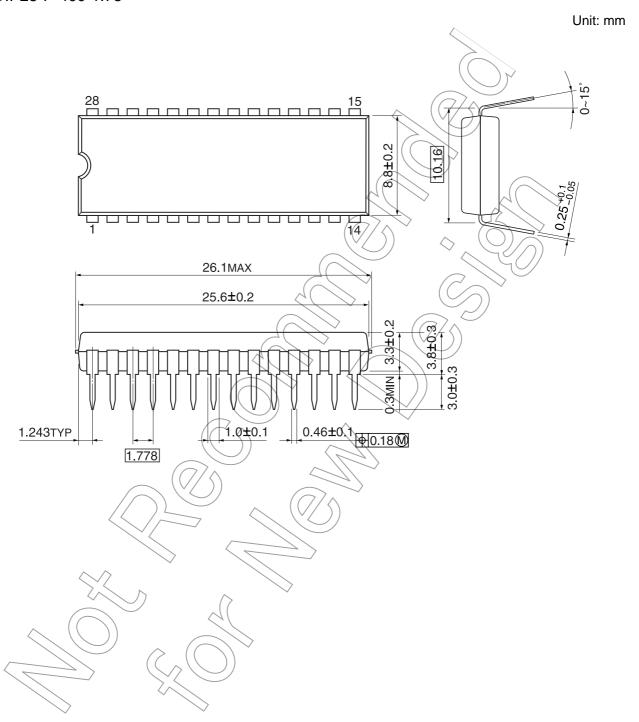
The publication date of this datasheet is printed at the lower right corner of this notification.



(Annex)

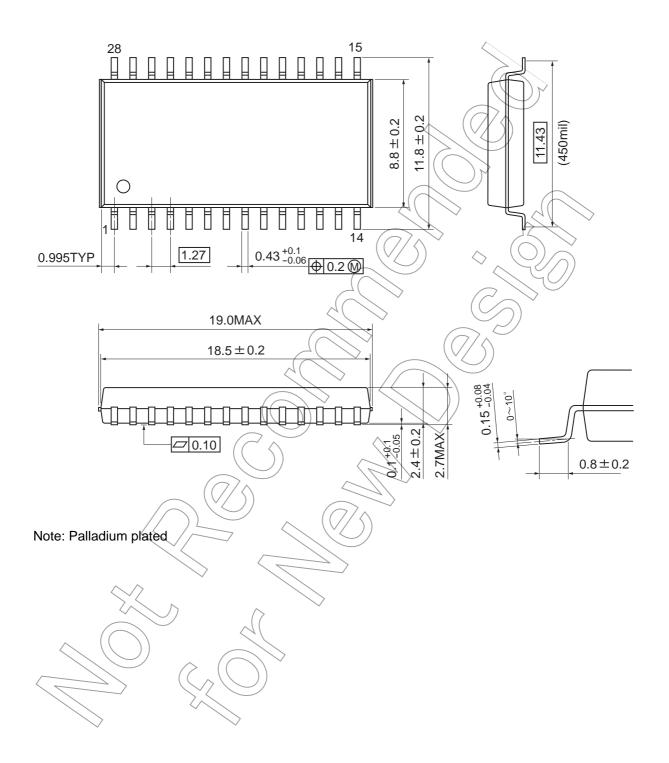
Package Dimensions

SDIP28-P-400-1.78



SOP28-P-450-1.27B

Unit: mm

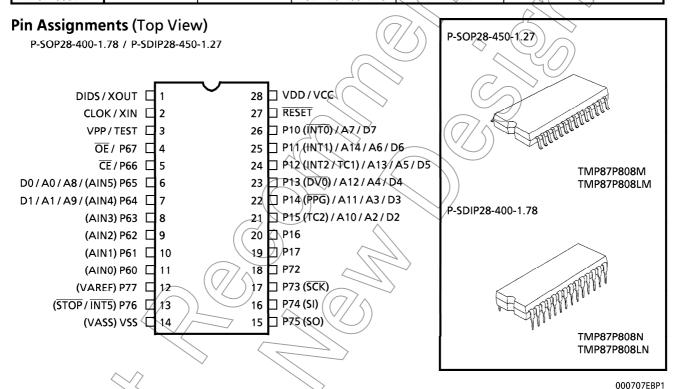


CMOS 8-Bit Microcontroller

TMP87P808M, TMP87P808N TMP87P808LM, TMP87P808LN

The 87P808/808L is a high-speed, high-performance 8-bit single chip microcomputer, which has 64K bits One-Time PROM. The 87P808/808L is pin compatible with the 87C408/808/408L/808L. The operations possible with the 87C408/808/408L/808L can be performed by writing programs to PROM. The 87P808/808L can write and verify in the same way as the TC57256AD using an adapter socket and a general-purpose PROM programmer.

Part No.	ROM	RAM	Package	Adapter socket	/ Operation Voltage Range
TMP87P808M			P-SOP28-450-1.27	BM11116	2.7 V to 5.5 V at 4.2 MHz
TMP87P808N	8 K × 8-bit	256 × 8-bit	P-SDIP28-400-1.78	BM11122	4.5 V to 5.5 V at 8 MHz
TMP87P808LM	0 K X 0-DIL	230 X 0-DIL	P-SOP28-450-1.27	BM11116	1.8 V to 4.0 V at 4.2 MHz
TMP87P808LN]		P-SDIP28-400-1.78	BM11122	1.8 V 10 4.0 V at 4.2 IVIHZ



For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance / Handling Precautions.

Quality and Reliability Assurance / Handling Precautions.

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quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's

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Pin Function

The 87P808/808L has two modes: MCU and PROM.

(1) MCU mode

In this mode, the 87P808/808L is pin compatible with the 87C408/808/408L/808L (fix the TEST pin at low level).

(2) PROM mode

Pin Name (PROM mode)	Input / Output	Functions	Pin name (MCU mode)
A14 to A8	lamont		P10 to P15, P64, P65
A7 to A0	Input	Program memory address inputs	P10 to P15, P64, P65
D7 to D0	I/O	Program memory data input/outputs	P10 to P15, P64, P65
CE		Chip enable signal input	P66
ŌĒ	Input	Output enable signal input	P67
VPP		+ 12.5 V / 5 V (Program supply voltage)	TEST
vcc	Power supply	+5V	VDD
GND		ov (//5)	vss
P17 to P16			
P63 to P60	1/0		
P77 to P72	1/0	PROM mode setting pins. Be fixed at low level.	
RESET			
XIN	Input		
XOUT	Output	Connect an 8 MHz oscillator to stabilize the internal st	tate.
VAREF			
VASS	Power supply	0 V (GND)	

Operational Description

The configuration and function of the 87P808/808L are the same as those of the 87C408/808/408L/808L, except in that a one-time PROM is used instead of an on-chip mask ROM.

1. Operating Mode

The 87P808/808L has two modes: MCU and PROM.

1.1 MCU Mode

The MCU mode is activated by fixing the TEST/VPP pin at low level.

In the MCU mode, operation is the same as with the 87C408/808/408L/808L/TEST/VPP pin cannot be used open because it has no built in pull-down resistance.)

1.1.1 Program Memory

The 87P808/808L have an 8 Kbytes (addresses E000 to FFFF_H in the MCU mode, addresses 6000 to 7FFF_H in the PROM mode) one-time PROM.

When the 87P808/808L is used as a system evaluation of the 87C408/808/408L/808L, the data is written to the program storage area shown in Figure 1-1.

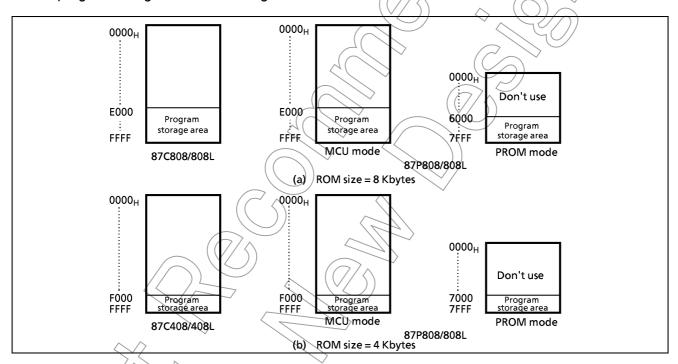


Figure 1-1. Program Memory Area

Note: Either write the data FFH to the unused area or set the general-purpose PROM programmer to access only the program storage area

1.1.2 Data Memory

The 87P808/808L has an 256 bytes data memory (static RAM).

1.1.3 Input / Output Circuits

(1) Control pins

The control pins of the 87P808/808L are the same as those of the 87C408/808L/808L except that the TEST pin has no built-in pull-down resistance.

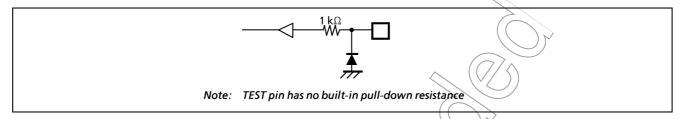


Figure 1-2. TEST Pin

(2) I/O port
The I/O circuits of 87P808/808L ports are the same as 87C408/808/408L/808L.

1.2 PROM Mode

The PROM mode is used to write and verify programs with a general-purpose PROM programmer.

Note: 24The high-speed programming mode (I II) can be used for program operation. (Please set the high-speed programming mode according to each manual of PROM programmer.) The 87P808/808L is not supported an electric signature mode.

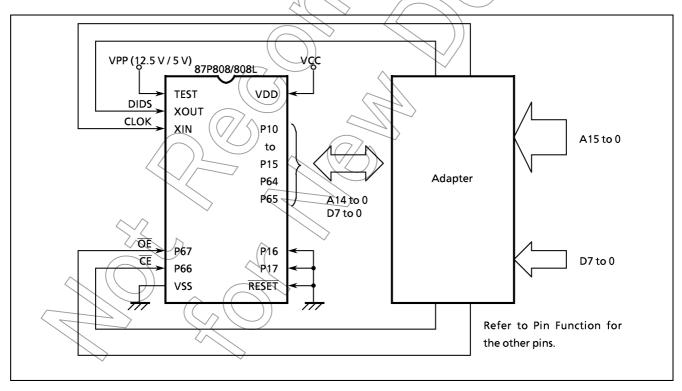


Figure 1-3. Setting for PROM Mode

1.2.1 Programming Flowchart (High-speed Programming Mode-I)

The high-speed programming mode is achieved by applying the program voltage (+ 12.5 V) to the V_{PP} pin when $V_{CC} = 6$ V. After the address and input data are stable, the data is programmed by applying a single 1ms program pulse to the \overline{CE} input. The programmed data is verified. If incorrect, another 1ms program pulse is applied and then the programmed data is verified. This process should be repeated (up to 25 times) until the program operates correctly. Programming for one address is ended by applying additional program pulse with width 3 times that needed for initial programming (number of programmed times \times 1 ms). After that, change the address and input data, and program as before. When programming has been completed, the data in all addresses should be verified with $V_{CC} = V_{PP} = 5$ V.

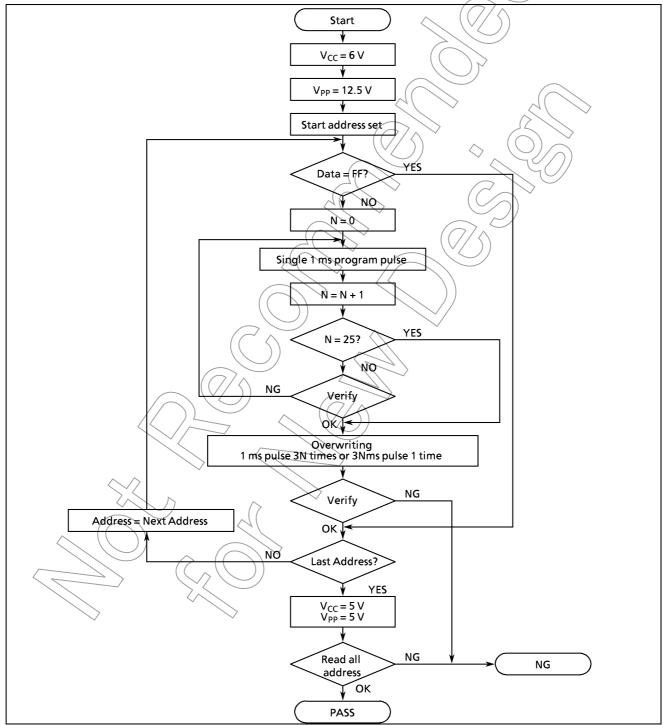


Figure 1-4. Flowchart of High-speed Programming Mode - I

1.2.2 Programming Flowchart (High-speed Programming Mode-II)

The high-speed programming mode is achieved by applying the program voltage (\pm 12.75 V) to the V_{PP} pin when Vcc = 6.25 V. After the address and input data are stable, the data is programmed by applying a single 0.1ms program pulse to the $\overline{\text{CE}}$ input. The programmed data is verified. If incorrect, another 0.1ms program pulse is applied and then the programmed data is verified. This process should be repeated (up to 25 times) until the program operates correctly. After that, change the address and input data, and program as before. When programming has been completed, the data in all addresses should be verified with Vcc = V_{PP} = 5 V.

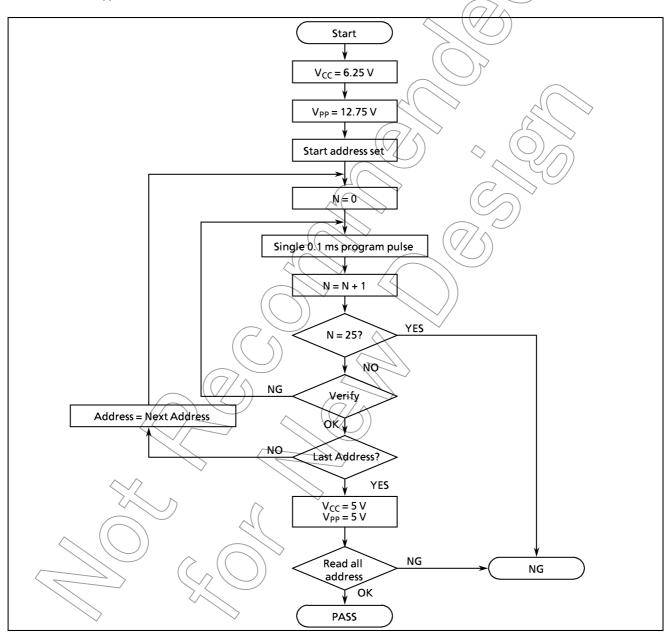


Figure 1-5. Flowchart of High-speed Programming Mode - II

1.2.3 Writing Method for General-purpose PROM Program

(1) Adapters

BM11116: TMP87P808M/TMP87P808LM BM11122: TMP87P808N/TMP87P808LN

(2) Adapter setting Switch (SW1) is set to side N.

(3) PROM programmer specifying

i) PROM type is specified to TC57256AD.

Writing voltage: 12.5 V (high-speed program I mode) 12.75 V (high-speed program II mode)

ii) Data transfer (copy) (note 1)

In TMP87P808/808L, EPROM is within the addresses 6000 to 7FFF_H. Data is required to be transferred (copied) to the addresses where it is possible to write. The program area in MCU mode and PROM mode is referred to "Program memory area" in Figure 1-1.

Ex. In the block transfer (copy) mode, executed as below.

ROM capacity of 4KB: transferred addresses F000 to FFFF_H to addresses 7000 to 7FFF_H

iii) Writing address is specified. (note 1)

Start address: 7000_H End address: 7FFF_H

(4) Writing

Writing/Verifying is required to be executed in accordance with PROM programmer operating procedure.

- Note 1: The specifying method is referred to the PROM programmer description. The data in addresses 0,000 to 5FFF_H must be specified to FF_H.
- Note 2: When MCU is set to an adapter or the adapter is set to PROM programmer, a position of pin 1 must be adjusted. If the setting is reversed, MCU, the adapter and PROM program is damaged.
- Note 3:TMP87P808/808L does not support the electric signature mode (hereinafter referred to as "signature"). If the signature is used in PROM program, a device is damaged due to applying 12 V ± 0.5 V to the address pin 9 (A9). The signature must not be used.

Electrical Characteristics

(1) 87P808

Absolute Maximum Ratings

 $(V_{SS} = 0 V)$

Parameter		Symbol	Conditions	Ratings	Unit
Supply Voltage		V_{DD}		- 0.3 to 6.5	٧
Program Voltage		V _{PP}	TEST /V _{PP} pin) + 0.3 to 13.0	V
Input Voltage		V _{IN}		- 0.3 to V _{DD} + 0.3	V
Output Voltage		V _{OUT}		-0.3 to $V_{DD} + 0.3$	V
	IOL	I _{OUT1}	P1, P6	3.2	mA
Output Current (Per 1 pin)	IOL	I _{OUT2}	P7 (Middle current port)	15	mA
	IOH	I _{OUT3}	P1, P6, P7	1.8	mA
	101	Σ l _{OUT1}	P1, P6	50	mA
Output Current (Total)	IOL	Σ l _{OUT2}	P7 (Middle current port)	60	mA
	ЮН	Σ l _{OUT3}	P1, P6, P7	30	mA
Power Dissipation [Topr = 70°C]		PD	SDIP	300 180	mW
Soldering Temperature (time)		Tsld		260 (10 s)	°C
Storage Temperature		Tstg		– 55 to 125	°C
Operating Temperature		Topr		– 30 to 70	°C

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to eatch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Operating Conditions

 $(V_{SS} = 0 \text{ V, Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Pins	Conditions		Min	Max	Unit
		$\langle \langle \langle \rangle \rangle$	fa (9-0.41) -	NORMAL mode	4.5		
			fc=8MHz	IDLE mode	4.5	5.5	
Supply Voltage	V _{DQ}		fc = 4.2 MHz	NORMAL mode	2.7		V
				IDLE mode	2.7		
	^			STOP mode	2.0		
	V _{IH1} Except hysteresis input		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		V _{DD} × 0.70		
Innut High Voltage	V _{H2} I	Hysteresis input	V _{DD} ≧ 4.5 V		$V_{DD} \times 0.75$.,	_v
Input High Voltage	VIH3		$2.7 \text{ V} \le \text{V}_{\text{D}} < 4.5 \text{ V}$		$V_{DD} \times 0.90$	V_{DD}	\ \ \
	y_{1H4}		V_{DD} < 2.7 V		$V_{DD} \times 0.95$		
	V _{IL1}	Except hysteresis input		> 4 5 1/		$V_{DD} \times 0.30$	
Input Low Voltage	V_{IL2}	Hysteresis input	V	_{DD} ≧ 4.5 V	0	$V_{DD} \times 0.25$	V
	V _{IL3}		$2.7 \text{ V} \le \text{V}_{DD} < 4.5 \text{ V}$			V _{DD} × 0.10	
Clask Fraguency	fo	VIN VOLIT	V _{DD} = 4.5 to 5.5 V		1.0	8.0	
Clock Frequency	fc XIN, XOUT		V _{DD} = 2.7 to 5.5 V		1.0	4.2	MHz

Note 1: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

Note 2: Clock frequency fc: Supply voltage range is specified in NORMAL mode and IDLE mode.

Note 3: Minimum of clock frequency: 1 MHz ≤ fcgck

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D.C. Characteristics

 $(V_{SS} = 0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	PINS	Conditions	Min	Тур.	Max	Unit
Hysteresis Voltage	V_{HS}	Hysteresis inputs		-	0.9	_	٧
	I _{IN1}	TEST	V FFV				
Input Current	I _{IN2}	Tri-state ports	$V_{DD} = 5.5 \text{ V}$	<u>-</u> 2)~	-	2	μ A
	I _{IN3}	RESET, STOP	$V_{IN} = 5.5 V / 0 V$				
	R _{IN1}	TEST		30	70	150	
Input Resistance	R _{IN2}	RESET		100	220	450	$\mathbf{k}\Omega$
	R _{IN3}	STOPi	i = 2 to 5	30	130	250	
Output Leak Current	I_{LO}	Tri-state ports	$V_{DD} = 5.5 \text{ V}, V_{OUT} = 5.5 \text{ W } 0 \text{V}$	-2	_	2	μ A
Output High Voltage	V_{OH2}	Tri-state ports Ports P1, P6	$V_{DD} = 4.5 \text{ V}, I_{OH} = 70.7 \text{ mA}$	4.1	_	_	٧
Low Output Voltage	V_{OL}	Except XOUT and P7	$V_{DD} = 4.5V, I_{OL} = 1.6 \text{ mA}$	~//		0.4	٧
Low Output Current	I _{OL3}	P7	$V_{DD} = 4.5 \text{ V}, V_{OL} = 1.0 \text{ V}$		Z	_	mA
Supply Current in NORMAL mode			fcgck fc/2 fc/4		7.0 4.4 2.8	7.0 5.1	
NORIVIAL Mode			fc/8 MHz	7	2.2	4.5	-
Supply Current in IDLE mode			V _{IN} = 5.3 V / 0.2 V fc/2 fc/2	// - - -	3.6 2.6 2.0	5.5 4.2 3.7	
mode			fc/8	 	1.7	3.5	mA
	I_{DD}		fc	 _	1.7	2.8	- '''
Supply Current in			feack fc/2	 _	1.1	2.0	
NORMAL mode			$V_{DD} = 3.0 \text{ V}$ fc/4	_	0.7	1.4	
			fc = 4.19 MHz	<u> </u>	0.9	1.6	
Supply Current in IDLE			$V_{IN} = 2.8 \text{ V} / 0.2 \text{V}$ fcqck $fc/2$	_	0.7	1.4	1
mode			fc/4	_	0.5	1.0	1
Supply Current in STOP mode			V _{DD} = 5.5 V V _{IN} = 5.3 V / 0.2 V	_	0.5	10	μΑ

Note 1: Typical values show those at Topr = 25°C, VDD = 5 V.

Note 2: Input Current I_{IN1}, I_{IN3}: The current through resistor is not included, when the input resistor (pull-up or pull-down) is contained.

Note 3: I_{DD} ; Except for I_{REF}

A/D Conversion Characteristics

 $(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 5.5 \text{V}, Topr = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Analog Reference Voltage	VAREF		2.7	-	V_{DD}	
Analog Reference Voltage	VASS			V_{SS}]
Analog Input Voltage Range	V _{AIN}		V _{ASS}	_	V _{AREF}	V
Analog Reference Current	I _{REF}	$V_{AREF} = 5.5 \text{ V}, V_{ASS} (V_{SS}) = 0.0 \text{ V}$	-	0.8	1.0	mA
Nonlinearity Error		$V_{DD} = 5.0 \text{ V}, V_{AREF} = 5.000 \text{ V}$	-	-	± 1	
Zero Point Error		$V_{ASS}(V_{SS}) = 0.000 \text{ V}$	_	_	± 1	LSB
Full Scale Error		or $V_{DD} = 2.7 \text{ V}, V_{ARFF} = 2.700 \text{ V}$	_	_	± 1	LOB
Total Error		V _{ASS} (V _{SS}) = 0.000 V	-	-	± 2	

Note: Quantizing error is not contained in those errors.

A.C. Characteristics (I)

 $(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
		In NORMAL mode				
Machine Cycle Timer	tcy	In IDLE mode	0.5	\rangle -	4	μS
High Level Clock Pulse Width	t _{WCH}	For external clock operation				
Low Level Clock Pulse Width	t _{WCL}	fc = 8 MHz	50	_	_	ns
A/D Conversion Time	+ .	ACK = 0		46		
A/D Conversion Time	t _{ADC}	ACK = 1		184	_	tcy
A/D Sampling Time	t _{AIN}		- /	Z 4		

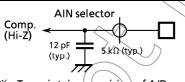
A.C. Characteristics (II)

 $(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 5.5 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

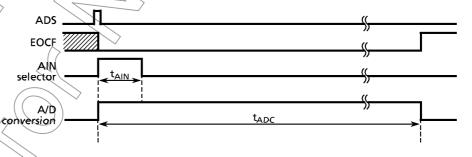
Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Machine Cycle Time	tcy	In NORMAL mode	0.95	-	4	μs
High Level Clock Pulse Width Low Level Clock Pulse Width	t _{WCH}	For external clock operation	110	-	-	ns
A/D Conversion Time		AÇK = 0		46		
AD Conversion Time	t _{ADC}	ACK=1	_	184	_	tcy
A/D Sampling Time	(t _A (N \		-	4		

Note: A/D conversion timing: Internal circuit for AIN0 to 5

A/D conversion timing



X To maintain a precision of A/D conversion, internal condenser must be charged until t_{AIN} is over.



Recommended Oscillating Conditions (${
m I}$)

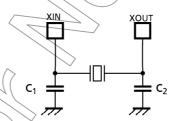
 $(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Oscillator	Oscillation Frequency	Recommended Oscillator		Recommende C ₁	ed Conditions C ₂
			KYOCERA	KBR8.0M	30 pF	30 pF
		8 MHz	MURATA	CSAC8.00MT	30 pF	30 pF
	Ceramic Resonator	(VDD = 4.5 to 5.5 V)	MURATA	CSA8.00MTZ CST8.00MTW CSTS8.00MT) –	_
High-frequency		4.19 MHz	MURATA	CSA4.19MG	30 pF	30 pF
Oscillation		(VDD = 2.7 to 5.5 V)	MURATA	CST4.19MGW	7	_
		4 MHz (VDD = 2.7 to 5.5 V)	KYOCERA	KBR4.0MS	30 pF	30 pF
	Crystal Oscillator	8 MHz (VDD = 4.5 to 5.5 V) 4 MHz (VDD = 2.7 to 5.5 V)	TOYOCOM	210B 8,0000 204B 4,000	20 pF	20 pF

Recommended Oscillating Conditions (II)

 $(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 5.5 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

		Oscillation			Recommended Conditions	
Parameter	Oscillator	Frequency	Recommen	ded Oscillator	C ₁	C ₂
		4.19 MHz	MURATA	CSA4.19MG	30 pF	30 pF
		(VDD = 2.7 to 5.5 V)	MURATA	CST4.19MGW	1	-
High-frequency		\sim	MURATA	CSA4.00MG	30 pF	30 pF
	Ceramic Resonator		_ \\	CSA4.00MGC	-	
Oscillation		√ ≰ MHz	MURATA	CST4.00MGW		
		(VDD = 2.7 to 5.5 V)		CSTC4.00MG	_	_
			MURATA	CSTCS4.00MG	_	_



(1) High-frequency Oscillation

Note: When used in high electric field such as a picture tube, the package is recommended to be electrically shielded to maintain a regular operation.

 $(V_{SS} = 0 V)$

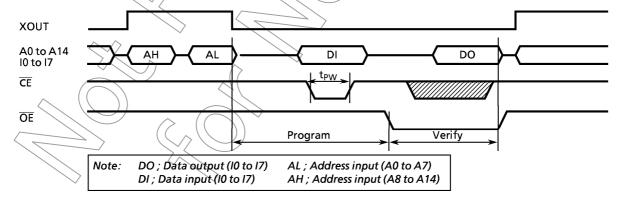
D.C. Characteristics, A.C. Characteristics

(1) Read Operation $(T_{opr} = 0 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		$V_{CC} \times 0.67$	((-)>	V _{CC}	V
Input Low Voltage	V _{IL4}		0		$V_{CC} \times 0.3$	V
Supply Voltage	V _{CC}		4,75	5,00	5.25	
Program Supply Voltage	V_{PP}		V _{CC} - 0.6	, , , , , , , , , , , , , , , , , , ,	V _{CC+0.6}	V
Address Set-up Time	t _{ASU}		400	-	-	ns
Address Access Time	t _{ACC}	$V_{CC} = 5.0 \pm 0.25 \text{ V}$	_/_	5tcyc	_	ns

(2) Program Operation (High speed write mode-1) (Topr = 25 ±5°C)

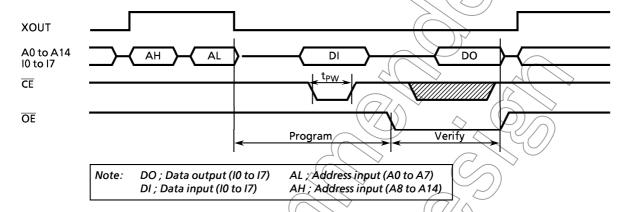
Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		$V_{CC} \times 0.7$	_	V_{CC}	V
Input Low Voltage	V _{IL4}) 0	_	$V_{CC} \times 0.12$	٧
Supply Voltage	$(v_{ec} \land)$		5.75	6.0	6.25	٧
Program Supply Voltage	V _{PP}		12.0	12.5	13.0	٧
Initial Program Pulse Width	t _{PW}	$V_{CC} \neq 6.0 \text{ V} \pm 0.25 \text{ V},$ $V_{DD} = 12.5 \text{ V} \pm 0.25 \text{ V}$	0.95	1.0	1.05	ms



- Note 1: When V_{cc} power supply is turned on or after, V_{PP} must be increased. When V_{cc} power supply is turned off or before, V_{PP} must be decreased.
- Note 2: The device must not be set to the EPROM programmer or picked up from it under applying the program voltage (12.5 V \pm 0.5 V) to the V_{PP} pin as the device is damaged.
- Note 3: Be sure to execute the recommended programing mode with the recommended programing adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

(3) Program Operation (High speed write mode -II) (Topr = 25 ± 5 °C)

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		$V_{CC} \times 0.7$	<u> </u>	V _{CC}	V
Input Low Voltage	V _{IL4}		0	1	$V_{CC} \times 0.12$	V
Supply Voltage	V _{CC}		6.00	6.25	6.50	V
Program Supply Voltage	V_{PP}		12.50	12.75	13.0	V
Initial Program Pulse Width	t _{PW}	$V_{CC} = 6.25 \text{ V} \pm 0.25 \text{ V},$ $V_{PP} = 12.75 \text{ V} \pm 0.25 \text{ V}$	0.095	701	0.105	ms



Note 1: When V_{cc} power supply is turned on or after, V_{PP} must be increased.

When V_{cc} power supply is turned off or before, V_{PP} must be decreased.

Note 2: The device must not be set to the EPROM programmer or picked up from it under applying the program voltage (12.5 V \pm 0.5 V) to the V_{PP} pin as the device is damaged.

Note 3: Be sure to execute the recommended programing mode with the recommended programing adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

Recommended EPROM Programmer

DATA I/O

UNISTTE (SITE40)

ADVANTEST

R4945A

AVAL DATA

PECKER11 MARK-II (version 5.5)

Electrical Characteristics

(1) 87P808L

Absolute Maximum Ratings

 $(V_{SS} = 0 V)$

Parameter		Symbol	Conditions		Ratings	Unit
Supply Voltage		V_{DD}		0.3 to 6.5	٧	
Program Voltage		V_{PP}	TEST /V _{PP} pin		- 0.3 to 13.0	٧
Input Voltage	: Voltage V _{IN}		- 0.3 to V _{DD} + 0.3	٧		
Output Voltage		V _{OUT}			- 0.3 to V _{DD} + 0.3	٧
	IOL	I _{OUT1}	P1, P6	75	3.2	mA
Output Current (Per 1 pin)	IOL	I _{OUT2}	P7 (Middle current port)	15	mA	
	IOL	I _{OUT3}	P1, P6, P7	- 1.8	mA	
	101	ΣI_{OUT1}	P1, P6		50	mA
Output Current (Total)	IOL	Σ I _{OUT2}	P7 (Middle current port)	^	60	mA
	IOL	Σ l _{OUT3}	P1, P6, P7	\Diamond	30)	mA
Danier Dissipation (Tana 7	0061	DD.		SDIP	300	\^/
Power Dissipation [Topr = 7	0.0]	PD		SOP	180	mW
Soldering Temperature (time)		Tsld		~~	260 (10 s)	°C
Storage Temperature	Tstg		– 55 to 125	°C		
Operating Temperature		Topr			– 30 to 70	°C

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Operating Conditions

 $(V_{SS} = 0 \text{ V, Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Pins	Conditions		Min	Max	Unit
			fc = 4.2 MHz	NORMAL mode			
Supply Voltage	V _{DD}		10 = 4.2 IVIN2	IDLE mode	1.8	4.0	V
	\nearrow		STOP mode				
Input High Voltage	V _∃	\wedge	>		V _{DD} × 0.90	V_{DD}	٧
Input Low Voltage) >	\mathcal{M}			0	$V_{DD} \times 0.10$	>
Clock Frequency	fc	XIN, XOUT	V _{DD} = 1.8 to 4.0 V		1.0	4.2	MHz

Note 1: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

Note 2: Clock frequency fc: Supply voltage range is specified in NORMAL mode and IDLE mode.

Note 3: Minimum of clock frequency: 1 MHz \leq fcgck

(

D.C. Characteristics

 $(V_{SS} = 0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	PINS	Condition	ons	\wedge	Min	Тур.	Max	Unit
Hysteresis Voltage	V_{HS}	Hysteresis inputs				-	0.9	-	V
	I _{IN1}	TEST	V _{DD} = 4.0 V						
Input Current	I _{IN2}	Tri-state ports	$V_{IN} = 4.0 \text{ V} / 0 \text{ V}$				-	2	μΑ
	I _{IN3}	RESET, STOP	VIN = 4.0 V / 0 V		\overrightarrow{a}				
	R _{IN1}	TEST	<u> </u>		// 5)	30	70	150	
Input Resistance	R _{IN2}	RESET		$\geq / /$		100	220	450	kΩ
	R _{IN3}	STOPi	i = 2 to 5			30	130	250	
Output Leakl Current	I_{LO}	Tri-state ports	$V_{DD} = 4.0 \text{ V}, V_{OUT} =$	4.0 V/C	yν̃	-2	_	2	μΑ
Output High Voltage	V_{OH2}	Tri-state ports	$V_{DD} = 4.0 \text{ V}, V_{OH} = 0.0 \text{ V}$		١	3.6		-	V
Output Low Voltage	V _{OL}	Except XOUT and P7	$V_{DD} = 4.0V, V_{QL} = 1.$	3 mA		\sim	_/	0.4	V
Output Low Current	I _{OL3}	P7	$V_{DD} = 4.0 \text{ V}, V_{OL} =$	<u></u> 50 ∨			6	-	mA
			$(\langle // \rangle)$		fc	\bigcirc	2.25	3.6	
Supply Current in				fcgck	fc/2		1).35	2.5	
NORMAL mode			$V_{DD} = 4 V$	regen	fc/4	1-7	0.9	1.9	
			fc = 4.19 MHz	(fc/8	7	0.7	1.65	
			$V_{1N} = 3.8 \text{ V} / 0.2 \text{V}$		Ť¢_) -	1.2	1.9	
Supply Current in IDLE mode			1,0	fcgck	fc/2	_	0.9	1.7	
			\rightarrow	(8)	fc/4	_	0.7	1.5	
		20			fc/8	_	0.6	1.4	
					fc	_	1.5	2.5	
Supply Current in				fçgck	fc/2	_	0.85	1.6	
NORMAL mode			V _{DD} = 3.0 V		fc/4	_	0.6	1.2	
			fc = 4.19 MHz		fc/8	_	0.4	1.0	mA
	I _{DD}		V _{IN} =2.8 × 0.2V		fc	-	0.8	1.4	
Supply Current in IDLE	טטי			fcgck	fc/2	_	0.55	1.1	
mode		($($ $)$ $)$			fc/4	_	0.45	0.9	
			7/^		fc/8	_	0.35	0.85	
					fc	-	0.9	1.3	
Supply Current in				fcgck	fc/2	_	0.5	0.8	
NORMAL mode			V _{DD} = 1.8 V		fc/4	-	0.3	0.45	. I
	\rightarrow		fc = 4.19 MHz		fc/8	-	0.2	0.35	
	\ \ \ \		V _{IN} = 1.6 V / 0.2V		fc	-	0.35	0.5	
Supply Current in IDLE		()		fcgck	fc/2	-	0.23	0.35	
mode					fc/4	-	0.17	0.26	
	<i>!)</i>				fc/8	-	0.14	0.24	
Supply Current in		$Y \geq (())$	V _{DD} = 4.0 V			_	0.5	10	μΑ
STOP mode			$V_{IN} = 3.8 \text{ V} / 0.2 \text{ V}$, ,

Note 1: Typical values show those at Topr = 25° C, VDD = 4 V.

Note 2: Input current I_{IN1} , I_{IN3} : The current through resistor is not included, when the input resistor (pull-up or pull-down) is

contained.

Note3: IDD; Except for IREF

A/D Conversion Characteristics (I)

 $(V_{DD} = 1.8 \text{ to } 4.0 \text{ V}, \text{Topr} = -30 \text{ to } 70^{\circ}\text{C}, V_{SS} = 0\text{V})$

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit	
Analag Reference Voltage	V_{AREF}		1.8	_	V_{DD}		
Analog Reference Voltage	V_{ASS}		V _{SS}			<u> </u>	
Analog Input Voltage Range	V_{AIN}		V _{ASS}) ~ -	V_{AREF}	٧	
Nonlinearity Error			~ (7/4)	_	± 2		
Zero Point Error		$\begin{vmatrix} 1.8 \text{ V} \le \text{V}_{AREF} < 2.7 \text{ V} \\ \text{V}_{AREF} \le \text{V}_{DD} \le 4.0 \end{vmatrix}$		-	± 2	LCD	
Full Scale Error		$V_{ASS}(V_{SS}) = 0.000V$ ACK = 1 (Note2)		-	± 2	LSB	
Total Error		.((_		± 4		

Note1: Quantizing error is not contained in those errors.

Note2: ACK; bit5 of ADCCR (#000E_H). conversion time = 184 tcy (175.6 µs/at fcgck ≠ 4.19 MHz)

A/D Conversion Characteristics (II)

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Analog Reference Voltage	V_{AREF}		(\(\sqrt{2.7} \)	_	V_{DD}	V
	V_{ASS}	4(> /	V _{SS}			V
Analog Input Voltage Range	V_{AIN}		\\ V _{ASS}	_	V _{AREF}	>
Analog Reference Current	I _{REF}	$V_{AREF} = 4.0V, V_{ASS}(V_{SS}) = 0.0V$		0.5	1.0	mA
Nonlinearity Error		V _{DD} = 4.0 V	_	_	± 1	
Zero Point Error		V _{AREF} = 4.000V V _{ASS} (V _{SS}) = 0.000V	_	-	± 1	LCD
Full Scale Error		V _{DD} = 2.7 V	-	-	± 1	LSB
Total Error		V _{AREF} = 2.700V V _{ASS} (V _{SS}) = 0.000V	_	-	± 2	

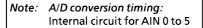
Note: Quantizing error is not contained in those errors.

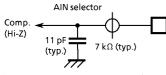


A.C. Characteristics

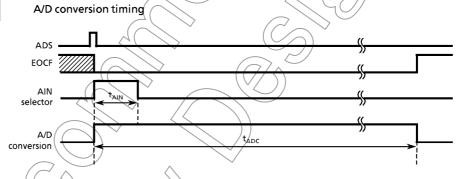
 $(V_{SS} = 0 \text{ V}, V_{DD} = 1.8 \text{ to } 4.0 \text{ V}, Topr = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
		In NORMAL mode				
Machine Cycle Time	tcy	In IDLE mode	0.95	> -	4	μS
High Level Clock Pulse Width	t _{WCH}	For external clock operation	(7/1)			
Low Level Clock Pulse Width	t _{WCL}	fc = 4.2 MHz	110	_	_	ns
A/D Conversion Time		ACK = 0		46		
A/D Conversion Time	t _{ADC}	ACK = 1		184	_	tcy
A/D Sampling Time	t _{AIN}		- 0	4	\Diamond	





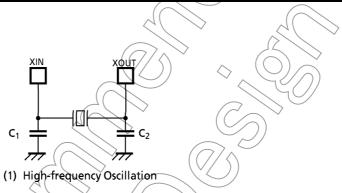
X To maintain a precision of A/D conversion, internal condenser must be charged until t_{AIN} is over.



Recommended Oscillating Conditions

 $(V_{SS} = 0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Oscillator	Oscillation	Recomme	nded Oscillator	Recommended Conditions		
rarameter	Oscillator	Frequency	Recommended Oscillator		C ₁	C ₂	
		4.19 MHz	MURATA	CSA4.19MG	30 pF	30 pF	
	(VDD = 2.7 to 5.5 V)	MURATA	CST4.19MGW		_		
High-frequency	l		MURATA	CSA4.00MG	30 pF	30 pF	
	Ceramic Resonator			CSA4.00MGC) –	1	
Oscillation		4 MHz	MURATA	CST4.00MGW			
		(VDD = 2.7 to 5.5 V)		CSTC4.00MG	-	1	
			MURATA	CSTCS4.00MG	1	1	



Note: When used in high electric field such as a picture tube, the package is recommended to be electrically shielded to maintain a regular operation.

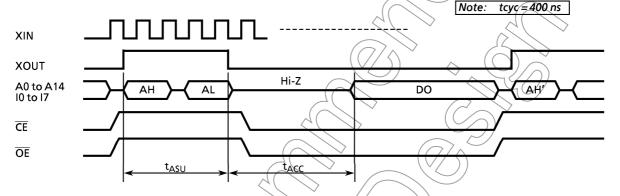


D.C. Characteristics, A.C. Characteristics

 $(V_{SS} = 0 V)$

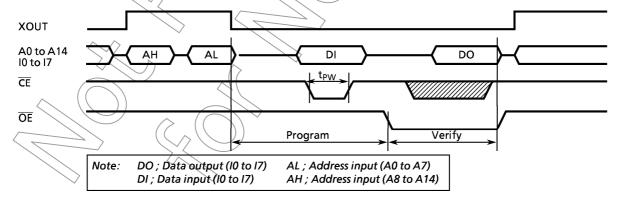
(1) Read Operation $(T_{opr} = 0 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		V _{CC} × 0.67	((-)>	V _{CC}	٧
Input Low Voltage	V _{IL4}		0		$V_{CC} \times 0.3$	V
Supply Voltage	V _{CC}		4,75	5,00	5.25	
Program Supply Voltage	V_{PP}		V _{CC} - 0.6	, , , , , , , , , , , , , , , , , , ,	V _{CC+0.6}	V
Address Set-up Time	t _{ASU}		400	-	-	ns
Address Access Time	t _{ACC}	V _{CC} = 5.0 ± 0.25 V	(5tcyc	_	ns



(2) Program Operation (High speed write mode-1) (Topr = 25 ±5°C)

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		$V_{CC} \times 0.7$	_	V _{CC}	V
Input Low Voltage	V _{IL4}) 0	_	$V_{CC} \times 0.12$	V
Supply Voltage	$(y_{gc} \land)$		5.75	6.0	6.25	V
Program Supply Voltage	V _{PP}		12.0	12.5	13.0	٧
Initial Program Pulse Width	t _{PW}	$V_{CC} \neq 6.0 \text{ V} \pm 0.25 \text{ V},$ $V_{PP} = 12.5 \text{ V} \pm 0.25 \text{ V}$	0.95	1.0	1.05	ms



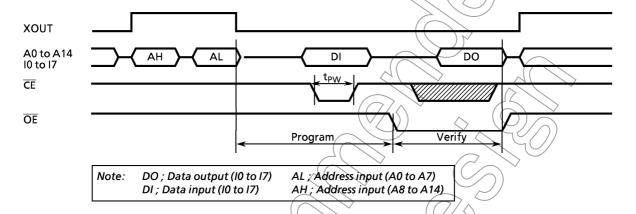
Note 1: When V_{cc} power supply is turned on or after, V_{PP} must be increased. When V_{cc} power supply is turned off or before, V_{PP} must be decreased.

Note2: The device must not be set to the EPROM programmer or picked up from it under applying the program voltage (12.5 V \pm 0.5 V) to the V_{PP} pin as the device is damaged.

Note3: Be sure to execute the recommended programing mode with the recommended programing adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

(3) Program Operation (High speed write mode -II) (Topr = 25 ± 5 °C)

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Input High Voltage	V_{IH4}		$V_{CC} \times 0.7$	<u> </u>	V _{CC}	V
Input Low Voltage	V_{IL4}		0	1-	$V_{CC} \times 0.12$	V
Supply Voltage	V _{CC}		6.00	6.25	6.50	V
Program Supply Voltage	V_{PP}		12.50	12.75	13.0	<
Initial Program Pulse Width	t _{PW}	$V_{CC} = 6.25 \text{ V} \pm 0.25 \text{ V},$ $V_{PP} = 12.75 \text{ V} \pm 0.25 \text{ V}$	0.095	701	0.105	ms



Note1: When V_{cc} power supply is turned on or after, V_{PP} must be increased. When V_{cc} power supply is turned off or before, V_{PP} must be decreased.

Note2: The device must not be set to the EPROM programmer or picked up from it under applying the program voltage (12.5 V \pm 0.5 V) to the V_{PP} pin as the device is damaged.

Note3: Be sure to execute the recommended programing mode with the recommended programing adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

Recommended EPROM Programmer

DATA I/O ADVANTEST UNISTTE (SITE40)

ADVANTEST

R4945A

AVAL DATA PECKER11 MARK-II (version 5.5)